BY TELEFAX TO:
(703) 872-9310

DOCKET NO.: 4029

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN THE MATTER OF THE APPLICATION FOR PATENT

OF: Michio OSADA et al.	Art Unit: 1722
SERIAL NO.: 09/705,237	Confirmation No.: 4586
FILED: November 2, 2000	EX.: Thukhanh T. Nguyen

FOR: Die Used for Resin-Sealing and Molding an Electronic Component

ASSISTANT COMMISSIONER FOR PATENTS
BOX RESPONSE - NO FEE
WASHINGTON, D.C. 20231

January 31, 2003

RESPONSE TO THE OFFICE ACTION OF OCTOBER 31, 2002 INCLUDING AN ATTACHED COVER SHEET WITH CERTIFICATE OF TELEFAX TRANSMISSION

Dear Sir:

Please amend the above identified application as follows.

In the Specification:

Please delete and replace the paragraph at **page 4, lines 16 to 19**, to read as follows:

Furthermore, if coating layer (A) has a tungsten content of approximately 10% by weight then electrolysis rapidly increases the layer's electrostatic stress and also decreases the layer's flexibility. This results in a crack in a surface of the coating layer.